

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
100V	1.7mΩ@10V	340A

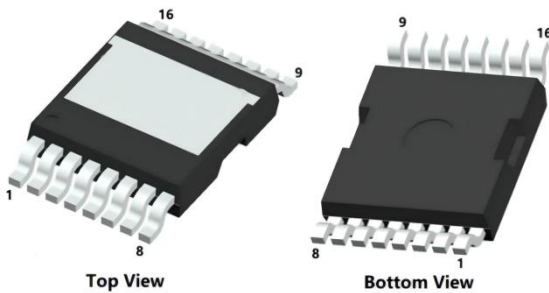
### Feature

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Suffix “-Q1” for AEC-Q101

### Application

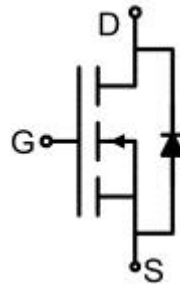
- High power inverter system
- BMS appliances

### Package

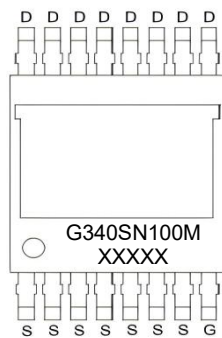


TOLT

### Circuit diagram



### Marking



### Absolute maximum ratings (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current <sup>1,3)</sup> (V <sub>GS</sub> =10V, Chip limitation)	I <sub>D</sub>	340	A
Continuous Drain Current <sup>1,3)</sup> (V <sub>GS</sub> =10V, T <sub>c</sub> =100°C)	I <sub>D</sub> (100°C)	240	A
Pulsed Drain Current (t <sub>p</sub> ≤10μs)	I <sub>DM</sub>	1360	A
Single Pulse Avalanche Energy <sup>2)</sup>	E <sub>AS</sub>	2722.5	mJ
Power Dissipation <sup>1,3)</sup>	P <sub>D</sub>	416	W
Thermal Resistance Junction to Case	R <sub>θJC</sub>	0.36	°C/W
Operating Junction Temperature	T <sub>J</sub>	-55 ~ +175	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +175	°C

### Electrical characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =1mA	100			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2	2.6	4	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		1.2	1.7	mΩ
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f =1MHz		10700		pF
Output Capacitance	C <sub>oss</sub>			2010		
Reverse Transfer Capacitance	C <sub>rss</sub>			35		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A		166		nC
Gate-Source Charge	Q <sub>gs</sub>			34		
Gate-Drain Charge	Q <sub>gd</sub>			49		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A R <sub>G</sub> =4.5Ω		30		nS
Turn-on rise time	t <sub>r</sub>			65		
Turn-off delay time	t <sub>d(off)</sub>			121		
Turn-off fall time	t <sub>f</sub>			107		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	I <sub>S</sub>				340	A
Diode Forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			1.2	V
Reverse Recovery Time	T <sub>rr</sub>	V <sub>GS</sub> =0V, V <sub>R</sub> =50V, I <sub>F</sub> =30A		92		nS
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt =-100A/μs		167		nC

Notes:

- 1) The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular.
- 2) T<sub>J</sub> =25°C, V<sub>G</sub> =10V, R<sub>θ</sub> =25Ω, L =5mH, I<sub>AS</sub> =33A.
- 3) Thermal resistance from junction to soldering point (on the exposed drain pad).
- 4) Guaranteed by design, not subject to production.

## Typical Characteristics

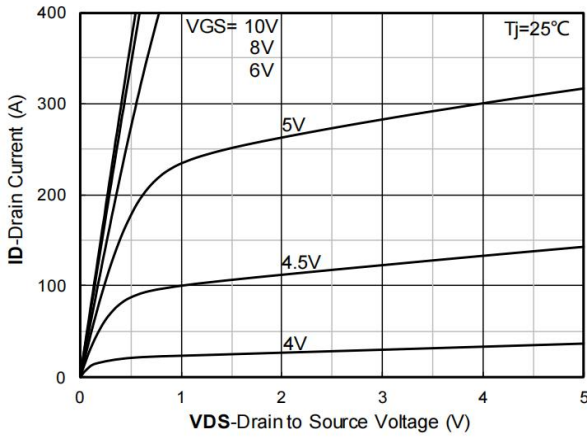


Figure 1. Output Characteristics

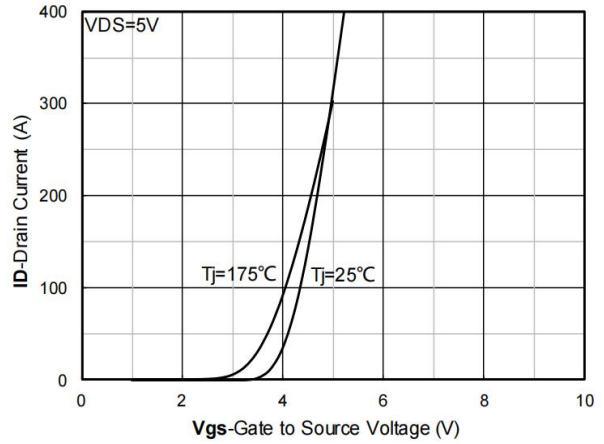


Figure 2. Transfer Characteristics

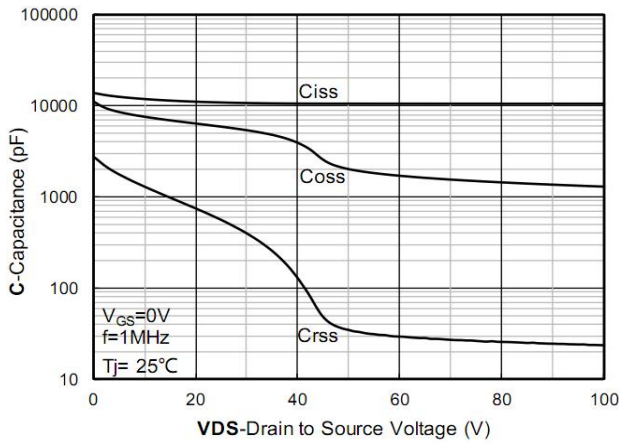


Figure 3. Capacitance Characteristics

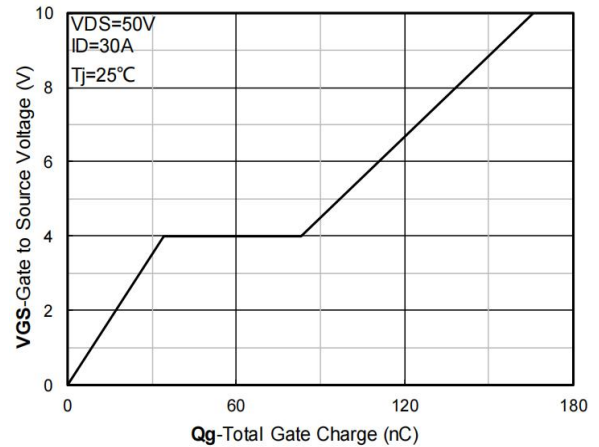


Figure 4. Gate Charge

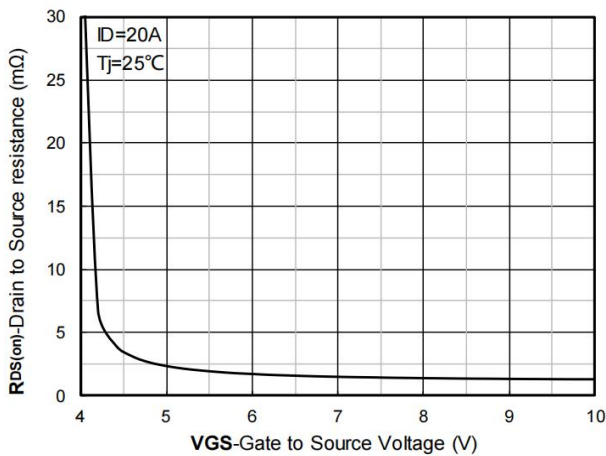


Figure 5. On-Resistance vs Gate to Source Voltage

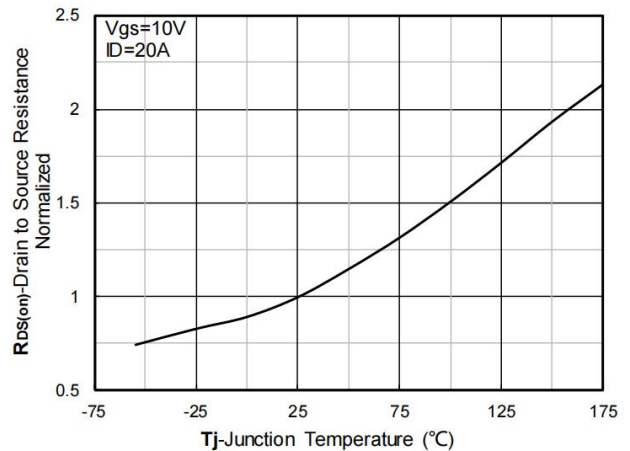


Figure 6. Normalized On-Resistance

## Typical Characteristics

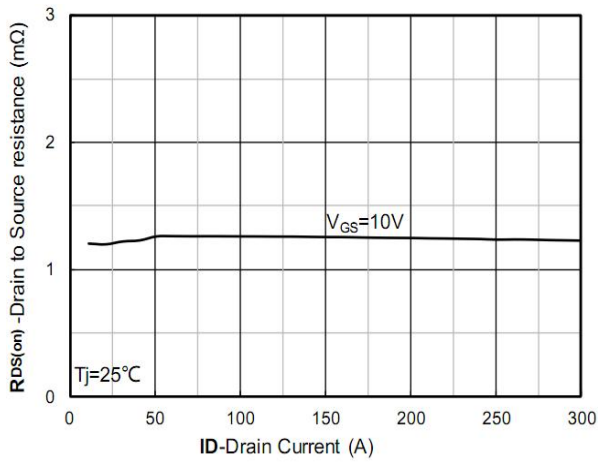


Figure 7.  $R_{DS(on)}$  vs. Drain Current

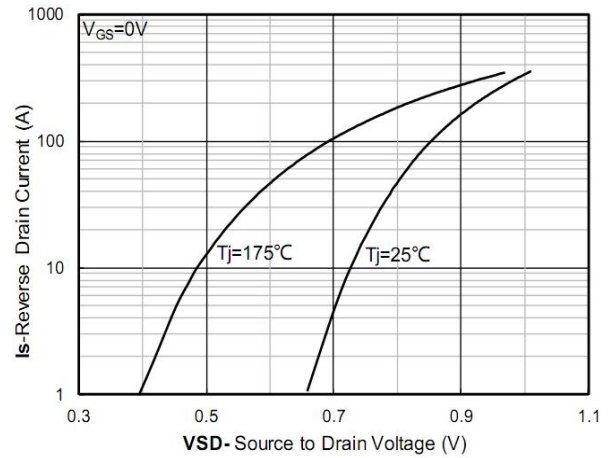


Figure 8. Forward characteristics of reverse diode

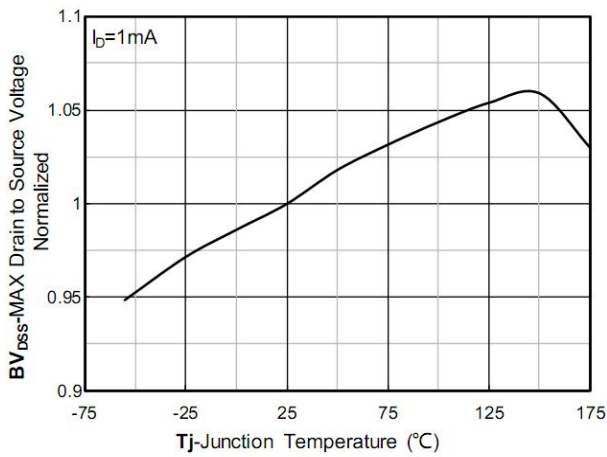


Figure 9. Normalized breakdown voltage

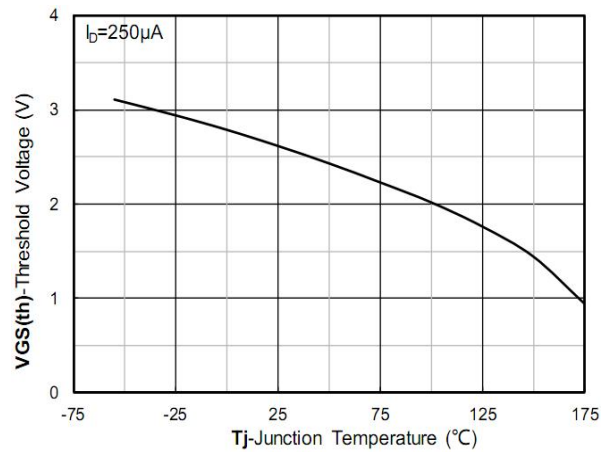


Figure 10. Gate Threshold voltage; typical values

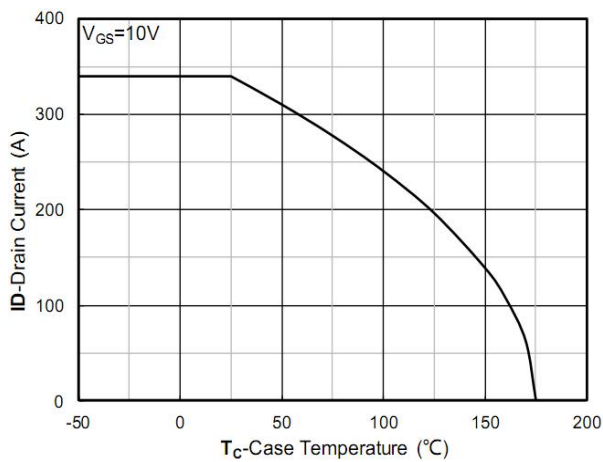


Figure 11. Current dissipation

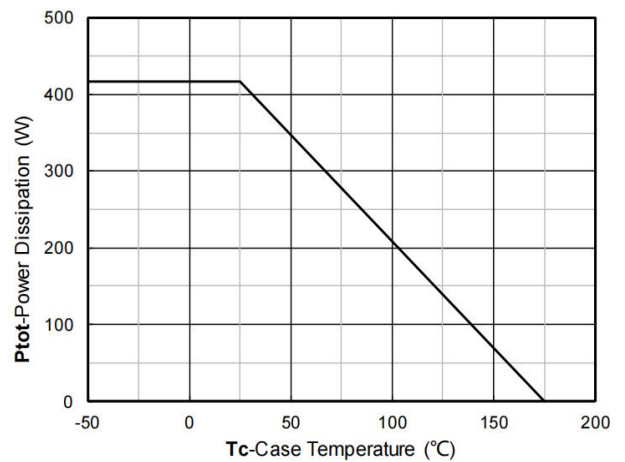


Figure 12. Power dissipation

## Typical Characteristics

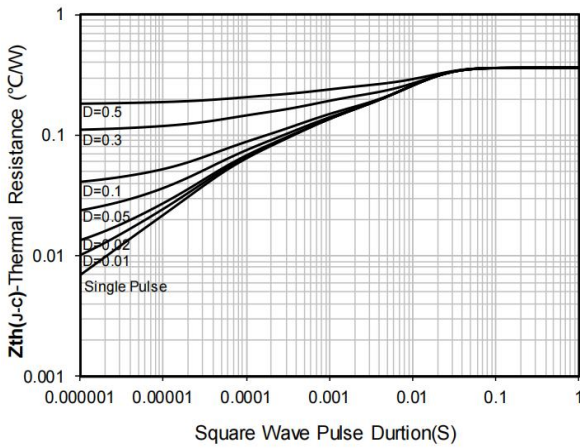


Figure 13. Maximum Transient Thermal Impedance

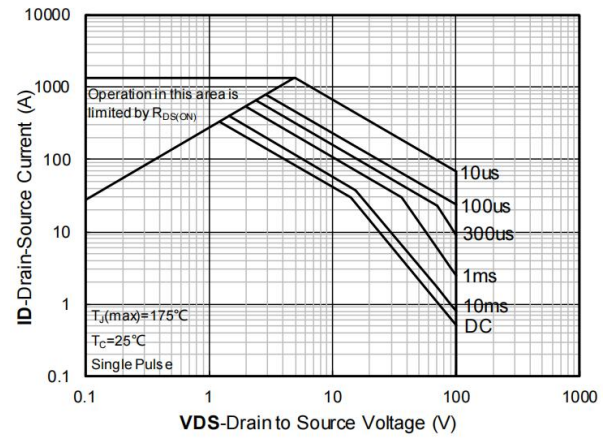
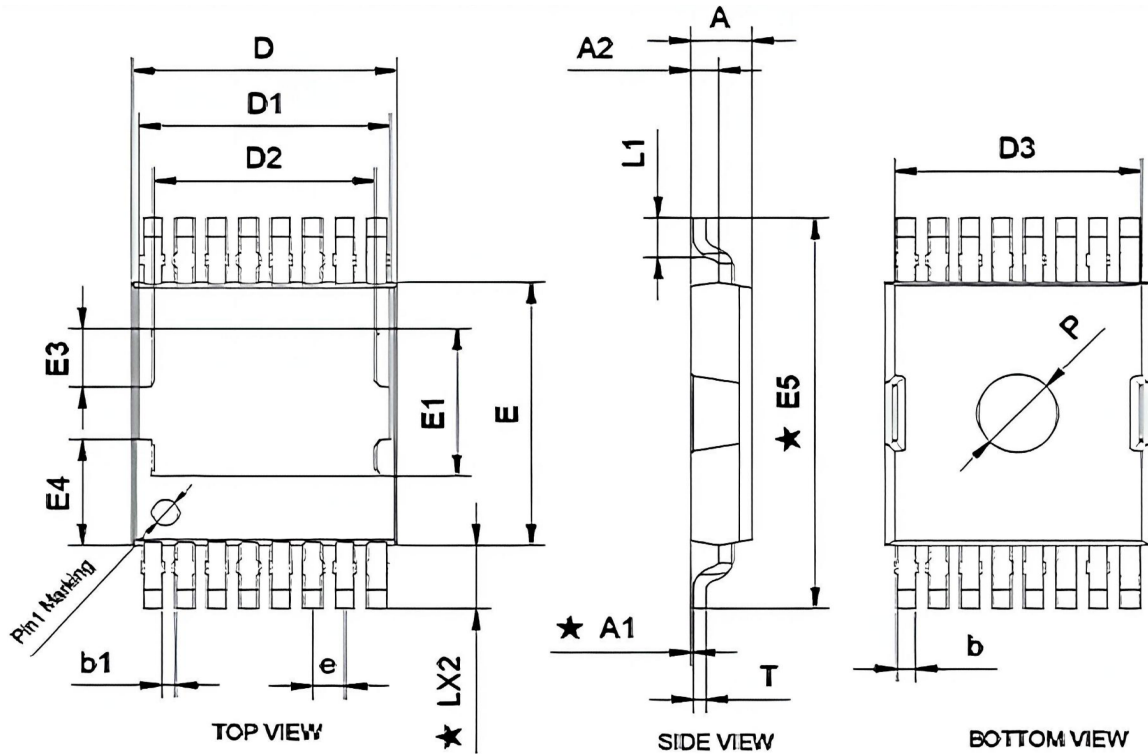


Figure 14. Safe Operation Area

### TOLT Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.250	2.350	0.089	0.093
A1	0.010	0.160	0.000	0.006
A2	0.990	1.090	0.039	0.043
b	0.600	0.800	0.024	0.031
b1	0.400	0.600	0.016	0.024
D	9.700	10.100	0.382	0.398
D1	9.360	9.560	0.369	0.376
D2	8.200	8.400	0.323	0.331
D3	9.170	9.370	0.361	0.369
e	1.200 BSC.		0.047 BSC.	
E	10.000	10.300	0.394	0.406
E1	5.470	5.870	0.215	0.231
E2	1.900	2.100	0.075	0.083
E3	2.050	2.450	0.081	0.096
E4	3.900	4.200	0.154	0.165
E5	14.800	15.200	0.583	0.598
L	2.200	2.700	0.087	0.106
L1	1.510 REF.		0.059 REF.	
T	0.458	0.558	0.018	0.022
P	2.800	3.200	0.110	0.126